

**NOTES: (UNLESS OTHERWISE SPECIFIED)**

- FABRICATE IN ACCORDANCE WITH IPC-6018B, PER IPC-6011, CLASS 2.
- ARTWORK FORMAT: GERBER 274X  
GERBER DATA SUPPLIED WITH DESIRED FINAL TRACE WIDTHS. PROCESS COMPENSATION TRACE WIDTH ADJUSTMENTS TO BE DONE BY PCB FABRICATOR.
- MATERIAL:  
NUMBER OF LAYERS: 3 LAYERS  
SILKSCREEN TOP: HIGH TEMPERATURE, NON-CONDUCTIVE, WHITE EPOXY BASED INK  
SOLDERMASK TOP: LPI (LIQUID PHOTO-IMAGEABLE), GREEN OR LDI (LASER DIRECT IMAGEABLE), GREEN. MAX FINISH THICKNESS OF SOLDERMASK TO BE 0.001in.  
METAL 1 (TOP): 0.5 oz TO START, 1.0 oz. FINISH, 2.0 oz WHEN EXTRA PLATING CYCLE AFTER COIN INSERTION.  
PREPREG ROGERS 6202, 0.005 inch THICK  
METAL 2 0.5 oz (PLATE TO 1.0 oz)  
CORE FR4, 0.028 inch (0.7 mm) THICK  
METAL 3 (BOTTOM): 0.5 oz TO START, 1.0 oz. FINISH, 2.0 oz WHEN EXTRA PLATING CYCLE AFTER COIN INSERTION.
- FINISH PLATING:  
IMMERSION SILVER per IPC-4553A, (6 - 18µm)
- FINISHED BOARD:  
THICKNESS: 0.0376 inch ±0.003
- COPPER IS PULLED BACK PER GERBER DATA FROM EDGE OF BOARD ON METAL 1 (TOP) AND METAL 2 (INTERNAL) EXCEPT AROUND CONNECTOR AREA. COPPER IS PULLED BACK PER GERBER DATA FROM EDGE OF BOARD ON METAL 3 (BOTTOM).
- PC BOARD OUTLINE TOLERANCE: ±0.002 inch (0.051 mm)
- METALIZATION MUST BE FREE FROM CONTAMINATION AND DEBRIS.
- BURRS SHALL NOT EXCEED 0.002 inch (0.051 mm).
- VIA PLATING/FILLING:  
A. PLATING TO BE 0.0007 inch (0.018 mm) MIN. THICKNESS UNLESS PLATED CLOSED.  
B. THRU-HOLE VIAS: LAYERS 1-3
- METAL 1 TOP AND METAL 3 BOTTOM SHALL BE PLANARIZED AFTER PLATING HOLES SHUT.  
MAX ALLOWABLE NEGATIVE FEATURE 0.0008in. MAX ALLOWABLE POSITIVE FEATURE 0.0003in.
- SOLDERMASK IN PLATED-THRU HOLES IS ACCEPTABLE AS LONG AS IT DOES NOT EXIST ON BACKSIDE OF BOARD.
- CONDUCTOR WIDTHS AND SPACING TO BE WITHIN 0.003 inch (0.076 mm) OF CAD DATABASE.
- ALL HOLES TO BE LOCATED WITHIN ±0.003 inch OF CAD DATABASE.
- NO VENDOR MARKING OR SERIALIZATION ALLOWED.
- DELIVER BOARDS BAGGED AS: SINGLES.
- NO ELECTRICAL TEST NEEDED.

**Drill Table - Top to Bottom (\*.Txt)**

Symbol	Count	Hole Size	Plated	Drill Layer Pair
A	500	0.010(0.25)	Plated	METAL_1_TOP - METAL_3_BOT
C	4	0.100(2.54)	Plated	METAL_1_TOP - METAL_3_BOT
D	2	0.160(4.06)	Plated	METAL_1_TOP - METAL_3_BOT
506 Total				

**Drill Table - Top to Metal 2 (\*.Tx2)**

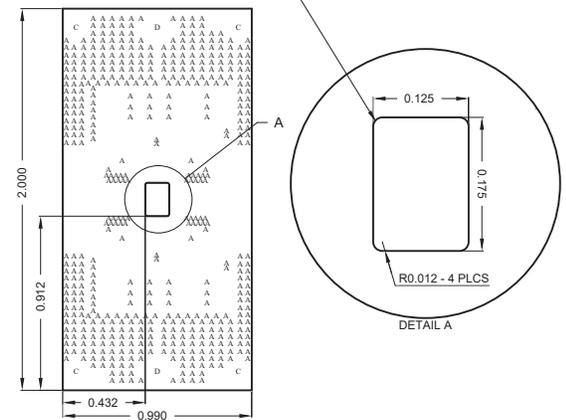
Symbol	Count	Hole Size	Plated	Drill Layer Pair
A	132	0.010(0.25)	Plated	METAL_1_TOP - METAL_2_MID
B	4	0.114(2.89)	Plated	METAL_1_TOP - METAL_2_MID
136 Total				

SUPPLIER MUST SEND EMAIL TO EVBOLD@QORVO.COM IF JOB IS PLACED ON HOLD  
SUPPLIER SHALL SEND A COPY OF FINAL WORKING GERBERS TO CEADS@QORVO.COM

**LAYER STACK LEGEND**

Material	Layer	Thickness	Dielectric Material	Type	Gerber
Surface Material	Top Overlay			Legend	GTO
Copper	Top Solder	0.0004in	Solder Resist	Solder Mask	GTS
Prepreg	METAL_1_TOP	0.0028in		Signal	GTL
Prepreg		0.0050in	Rogers 6202	Dielectric	
CF-004	METAL_2_MID	0.0017in		Signal	G1
Prepreg		0.0050in	370HR	Dielectric	
Core		0.0210in	LAM 370HR	Dielectric	
Copper	METAL_3_BOT	0.0017in		Signal	GBL
Total thickness: 0.0376in					

Copper Coin To Be Placed in Center Of DUT  
18, 19, 20, 21, 22



- COPPER COIN APERTURE TO BE EDGE PLATED, METAL 1, 2, AND METAL 3 TO BE PLATED COMPLETELY ALONG COPPER APERTURE EDGE
- COPPER COIN MATERIAL: OXYGEN FREE HIGH CONDUCTIVITY COPPER UWS CDA 101, 102, OR 103, ASTM B187, ASTM B152.
- COIN:  
0.125 X 0.175 inch (3.175 mm X 4.445 mm) SQUARE INSERT.  
FLATNESS AT COIN AREA TO BE FLUSH TO METAL 1 AND METAL 3 WITHIN +0.001/-0.001.
- PLATING BETWEEN COPPER COIN AND METAL 1 & METAL 3 TO BE CONTINUOUS. (UNINTERRUPTED).
- TOP OF COPPER COIN TO BE PLATED TO METAL 1. BOTTOM OF COIN TO BE PLATED TO METAL 3.

\* FOR MULTIPLE DRILL PROCESS JOBS SEE: \*DRL, \*DR1, \*DR2, etc.

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES	SAP MATERIAL NUMBER: 293139				
APPROVAL AND RELEASE RECORDS MAINTAINED IN PDE	DATE: 11/05/19				
DESIGNER: JAMES JACKSON	ENGR: WAYNE BRINLEE	TITLE: QPA2575 EVALUATION PCB DESIGN PACKAGE			
INTERPRET DRAWING PER ANSIS/ASME Y14.5 - 2009	PDE CONTROLLED	SIZE: B	DOCUMENT NUMBER: QPA2575-4000	PROTOTYPE INSTANCE: N/A	REV: A
THIRD ANGLE PROJECTION	DO NOT SCALE DRAWING	SHEET 1 OF 7		CAD: ALTIUM DESIGNER	SCALE: 2:1

Current Date & Time: 12/19/2019 10:57

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